







# U304, U305, U306 P-Channel JFET

#### **Features**

- InterFET P0099F Geometry
- Typical Noise: 8 nV/VHz
- Fast Switching
- RoHS Compliant
- SMT, TH, and Bare Die Package options.

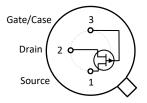
## **Applications**

- · Analog Switch
- Chopper

### Description

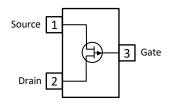
The 30V InterFET U304, U305, and U306 JFET's are targeted for choppers and switching designs. The on resistance is typically less than 100 Ohms at room temperatures. The TO-72 package is hermetically sealed and suitable for military applications.

#### **TO-18 Bottom View**



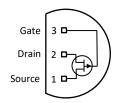


#### **SOT23 Top View**





**TO-92 Bottom View** 





#### **Product Summary**

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Parameters		U304 Min	U305 Min	U306 Min	Unit
$BV_GSS$	Gate to Source Breakdown Voltage	30	30	30	V
I <sub>DSS</sub>	Drain to Source Saturation Current	-30	-15	-5	mA
V <sub>GS(off)</sub>	Gate to Source Cutoff Voltage	5	3	1	V

#### Ordering Information Custom Part and Binning Options Available

Part Number	Description	Case	Packaging
U304; U305; U306	Through-Hole	TO-18	Bulk
PNU304; PNU305; PNU306	Through-Hole	TO-92	Bulk
SMPU304; SMPU305; SMPU306	Surface Mount	SOT23	Bulk
	7" Tape and Reel: Max 3,000 Pieces		Minimum 1,000 Pieces
SMPU304TR; SMPU305TR; SMPU306TR	13" Tape and Reel: Max 9,000 Pieces	SOT23	Tape and Reel
	Chip Orientated Tray		
U304COT; U305COT; U306COT	(COT Waffle Pack)	СОТ	400/Waffle Pack
	Chip Face-up Tray		
U304CFT; U305CFT; U306CFT	(CFT Waffle Pack)	CFT	400/Waffle Pack



**Disclaimer:** It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.









## **Electrical Characteristics**

Maximum Ratings (@ T<sub>A</sub> = 25°C, Unless otherwise specified)

	Parameters	Value	Unit
$V_{RGS}$	Reverse Gate Source and Gate Drain Voltage	30	V
I <sub>FG</sub>	Continuous Forward Gate Current	-50	mA
PD	Continuous Device Power Dissipation	350	mW
Р	Power Derating	2.8	mW/°C
Τı	Operating Junction Temperature	-55 to 125	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

Static Characteristics (@ TA = 25°C, Unless otherwise specified)

			U304		U305		U306		
	Parameters	Conditions	Min	Max	Min	Max	Min	Max	Unit
V <sub>(BR)GSS</sub>	Gate to Source Breakdown Voltage	$V_{DS} = 0V$ , $I_G = 1\mu A$	30		30		30		٧
I <sub>GSS</sub>	Gate to Source Reverse Current	$V_{GS} = 20V$ , $V_{DS} = 0V$ , $T_A = 25$ °C $V_{GS} = 20V$ , $V_{DS} = 0V$ , $T_A = 125$ °C		500 1		500 1		500 1	pΑ μΑ
V <sub>GS(OFF)</sub>	Gate to Source Cutoff Voltage	$V_{DS} = -15V$ , $I_D = -1\mu A$	5	10	3	6	1	4	V
I <sub>D(OFF)</sub>	Drain Cutoff Current	$V_{DG}$ = -15V, $V_{GS}$ = ( ), $T_A$ = 25°C $V_{DG}$ = -15V, $V_{GS}$ = ( ), $T_A$ = 125°C		-500 -1 (12)		-500 -1 (7)		-500 -1 (3)	nΑ μΑ V
I <sub>DSS</sub>	Drain to Source Saturation Current	$V_{DS} = -15V$ , $V_{GS} = 0V$ (Pulsed)	-30	-90	-15	-60	-5	-25	mA
V <sub>DS(ON)</sub>	Drain to Source ON Voltage	$V_{GS} = OV$ , $I_D = ()$		-1.3 (-15)		-0.8 (-7)		-0.6 (-5)	V mA

**Dynamic Characteristics** (@ TA = 25°C, Unless otherwise specified)

			U304		U305		U306		
	Parameters	Conditions	Min	Max	Min	Max	Min	Max	Unit
R <sub>DS(ON)</sub>	Drain to Soure ON Resistance	I <sub>D</sub> = 0A, V <sub>GS</sub> = 0V, f = 1kHz		85		110		175	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz		27		27		27	pF
Crss	Reverse Transfer Capacitance	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ( ), f = 1MHz		7 (12)		7 (7)		7 (5)	pF V
t <sub>d(ON)</sub>	Turn ON Delay Time	$V_{GS(ON)} = 0V$ U304: $V_{DD} = -10V$ , $V_{GS(OFF)} = 12V$ ,		20		25		25	nS
tr	Rise Time	$R_L = 580\Omega$ , $I_{D(ON)} = -15mA$ <b>U305:</b> $V_{DD} = -6V$ , $V_{GS(OFF)} = 7V$ ,		15		25		35	nS
t <sub>f</sub>	Fall Time	$R_L = 743\Omega$ , $I_{D(ON)} = -7mA$ <b>U306:</b> $V_{DD} = -6V$ , $V_{GS(OFF)} = 5V$ ,		25		40		60	nS
t <sub>d(OFF)</sub>	Turn OFF Delay Time	$R_L = 1800\Omega$ , $I_{D(ON)} = -3mA$		10		15		20	nS



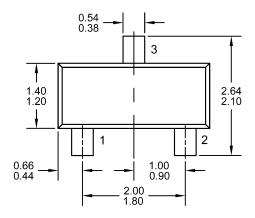


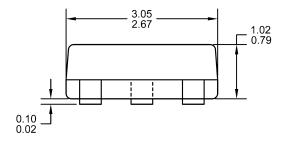




# SOT23 (TO-236AB) Mechanical and Layout Data

## **Package Outline Data**





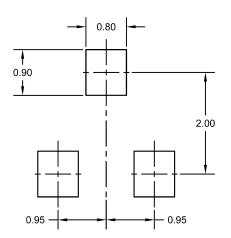
0.61 0.45 0.27 0.13 0.27 0.13

0.15

0.09

- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.12 grams
- 3. Molded plastic case UL 94V-0 rated
- For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

### **Suggested Pad Layout**



- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.



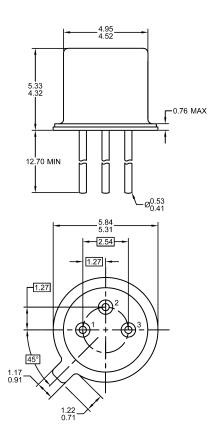






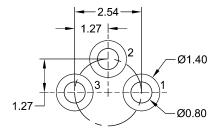
# **TO-18 Mechanical and Layout Data**

## **Package Outline Data**



- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.29 grams
- Bulk product is shipped in standard ESD shipping material
- 4. Refer to JEDEC standards for additional information.

# **Suggested Through-Hole Layout**



- 1. All linear dimensions are in millimeters.
- The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.



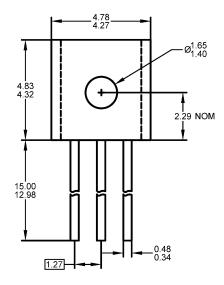


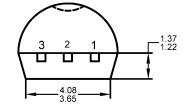


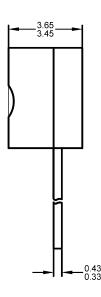


# **TO-92 Mechanical and Layout Data**

## **Package Outline Data**

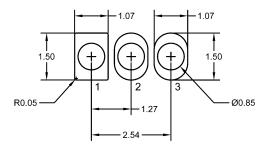






- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.19 grams
- 3. Molded plastic case UL 94V-0 rated
- Bulk product is shipped in standard ESD shipping material
- 5. Refer to JEDEC standards for additional information.

### **Suggested Through-Hole Layout**



- 1. All linear dimensions are in millimeters.
- The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.